AMPLEON

Package outline

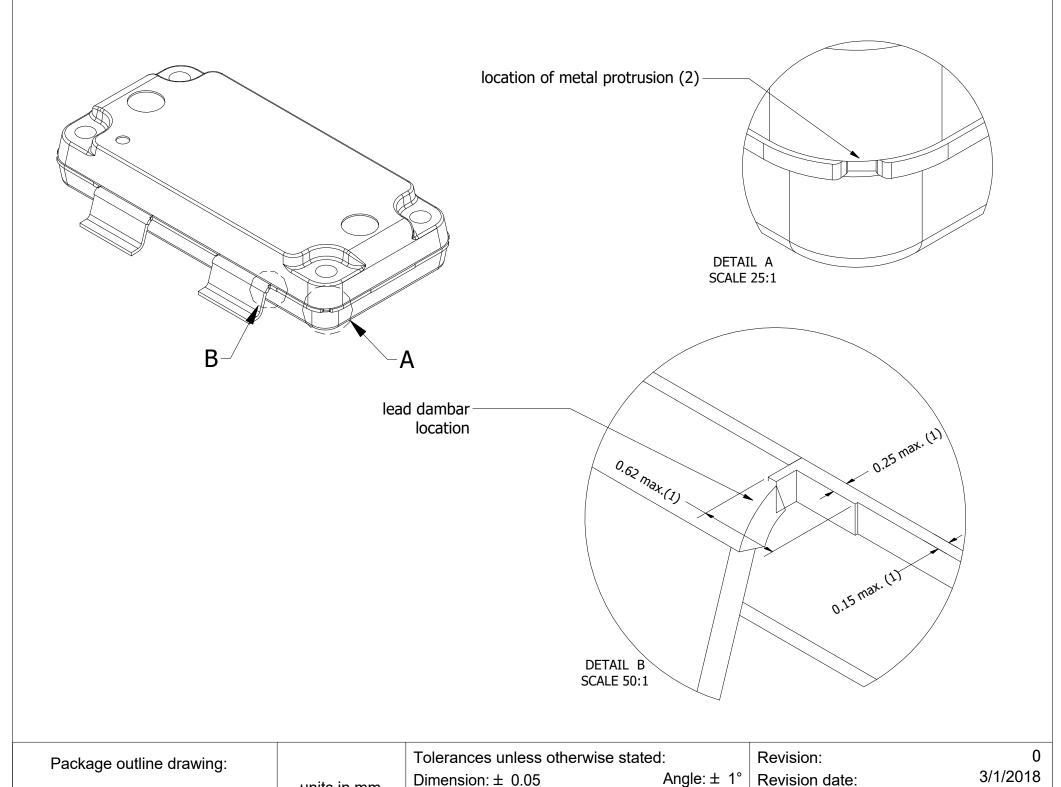
OMP-780-4G-1 -(18.01) - 0.22 ± 0.05 (15.44)(2.15)8.85 (0.75)Α **⊕** 0.05 A R1.38 \bigcirc 13.20 ± 0.30 16.00 9.96(1) (7.04) \emptyset 2.00 $0.1 \overline{\vee}$ R0.16 max. metal protrusion 4x (ground) in corners (2) ф 0.25 В 3.85(3)DETAIL C Ф 0.05 В 20.75(1) SCALE 25:1 $3.92^{\,+0.08}_{\,-0.03}$ R1.00 Н 0.95 ± 0.15 R0.32 В 20.57 -0.10(0.20) compound rim all around the perimeter of the heatsink $0.00^{\,+0.06}_{\,-0.02}\,(6)$ Gage plane pin 5 (4) R0.60(4x)0.35 (7) Seating plane Min. 15.5 Min. 18.5 Tolerances unless otherwise stated: 0 Revision: Package outline drawing: 3/1/2018 Angle: ± 1° Dimension: ± 0.05 Revision date: units in mm. OMP-780-4G-1 Third angle projection Sheet 1 of 2



Package outline

OMP-780-4G-1

Drawing Notes	
Items	Description
	Dimensions are excluding mold protrusion. Areas located adjacent to the leads have a maximum mold protrusion of 0.25
(1)	mm (per side) and 0.62 mm max. in length. At all other areas the mold protrusion is maximum 0.15 mm per side. See also
	detail B.
(2)	The metal protrusion (tie bars) in the corner will not stick out of the molding compound protrusions (detail A).
(3)	The lead dambar (metal) protrusions are not included. Add 0.14 mm max to the total lead dimension at the dambar location.
(4)	The hatched area indicated the exposed heatsink.
(5)	The leads and exposed heatsink are plated with matte Tin (Sn).
(6)	Dimension is measured with respect to the bottom of the heatsink Datum H. Positive value means that the bottom of the
(6)	heatsink is higher than the bottom of the lead.
(7)	Gage plane (foot length) to be measured from the seating plane.



OMP-780-4G-1

units in mm.

Sheet 2 of 2

Third angle projection